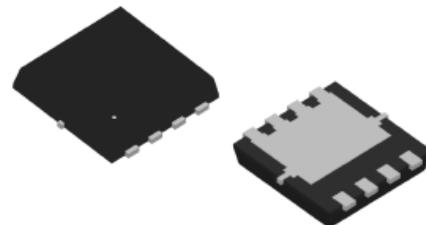


WNM3040

Single N-Channel, 30V, 19A, Power MOSFET

[Http://www.sh-willsemi.com](http://www.sh-willsemi.com)

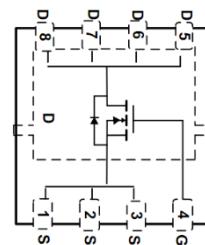
V_{DS} (V)	Typical R_{DS(on)} (mΩ)
30	12.0 @ V _{GS} =10V
	17.5 @ V _{GS} =4.5V



Descriptions

The WNM3040 is N-Channel enhancement MOS Field Effect Transistor. Uses advanced trench technology and design to provide excellent R_{DS(ON)} with low gate charge. This device is suitable for use in DC-DC conversion, power switch and charging circuit. Standard Product WNM3040 is Pb-free.

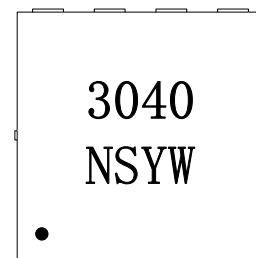
PDFN3333-8L



Pin configuration (Top view)

Features

- Trench Technology
- Supper high density cell design
- Excellent ON resistance
- Extremely Low Threshold Voltage
- Small package PDFN3333-8L



3040 =Device Code
NS = Special Code
Y = Year
W = Week(A~z)

Applications

- DC/DC converters
- Power supply converters circuit
- Load/Power Switching for portable device

Marking

Order information

Device	Package	Shipping
WNM3040-8/TR	PDFN3333-8L	3000/Tape&Reel

Absolute Maximum ratings

Parameter	Symbol	Maximum	Unit
Drain-Source Voltage	V _{DS}	30	V
Gate-Source Voltage	V _{GS}	±20	
Continuous Drain Current ^d	I _D	19	A
		15	A
Pulsed Drain Current ^c	I _{DM}	67	A
Continuous Drain Current	I _{DSM}	13	A
		10	
Avalanche Energy L=0.3mH	E _{AS}	12	mJ
Power Dissipation ^b	P _D	14	W
		6	
Power Dissipation ^a	P _{DSM}	4.0	W
		2.6	
Operating Junction Temperature	T _J	-55 to 150	°C
Storage Temperature Range	T _{STG}	-55 to 150	°C

Thermal resistance ratings

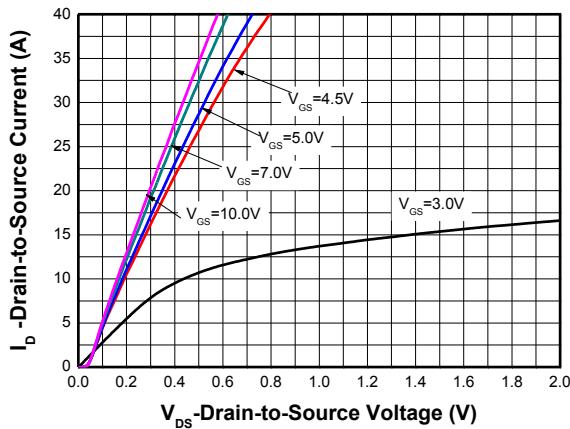
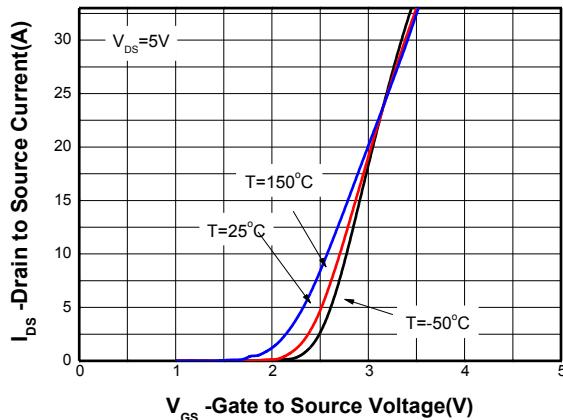
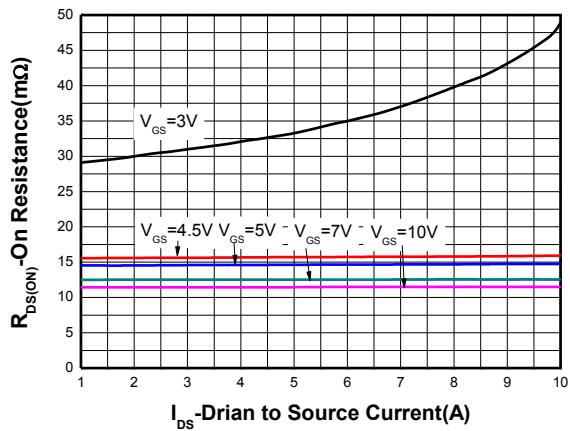
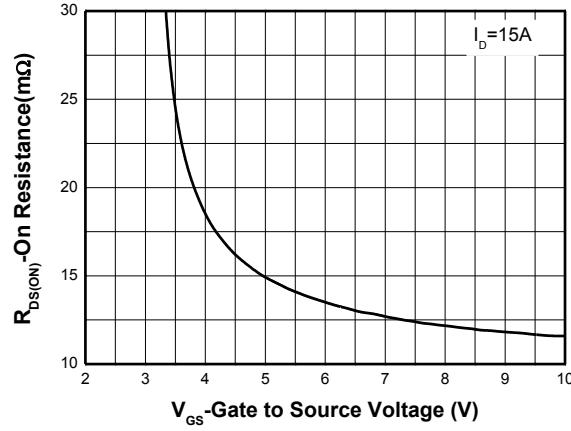
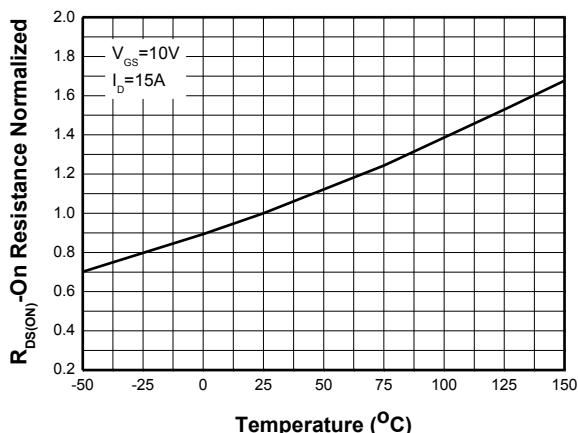
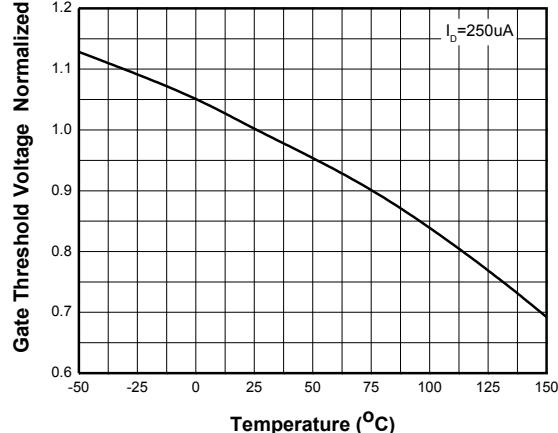
Single Operation					
Parameter	Symbol	Typical	Maximum	Unit	
Junction-to-Ambient Thermal Resistance ^a	t ≤ 10 s	R _{θJA}	25	31	°C/W
	Steady State		51	64	
Junction-to-Case Thermal Resistance	Steady State	R _{θJC}	7.2	9	

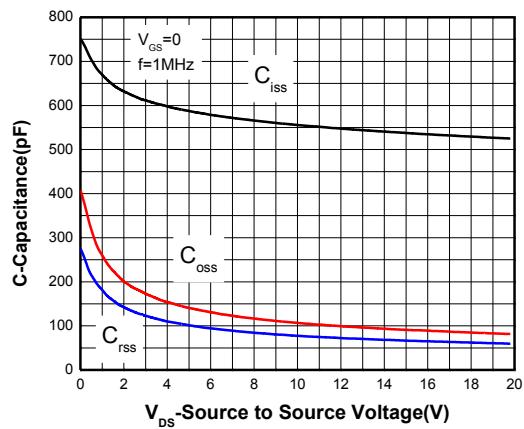
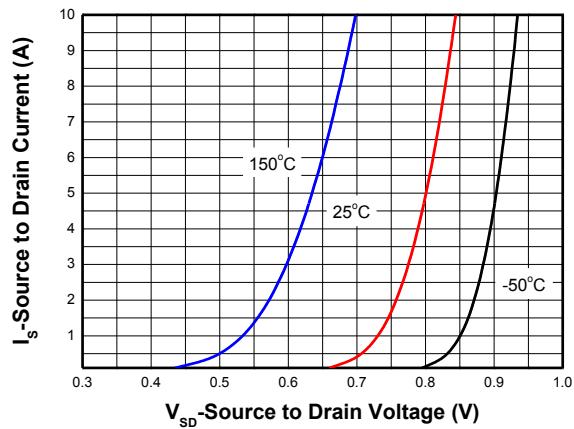
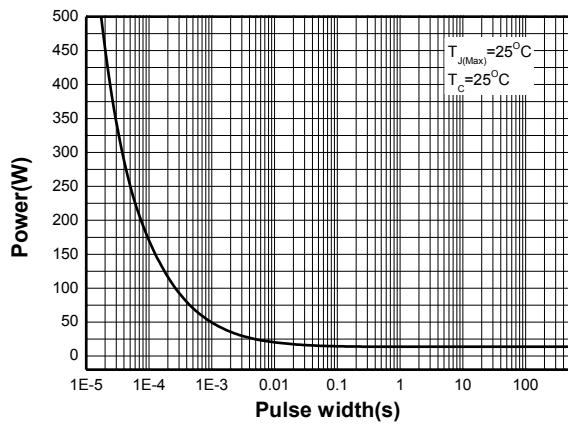
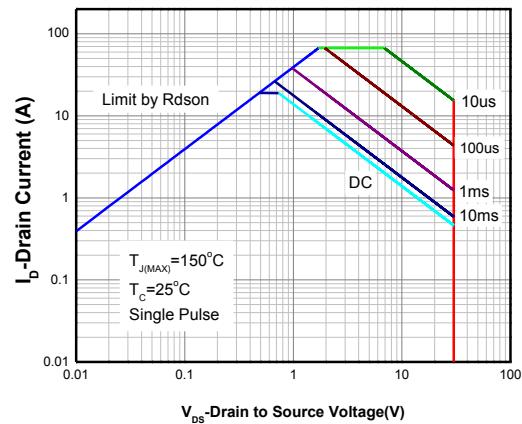
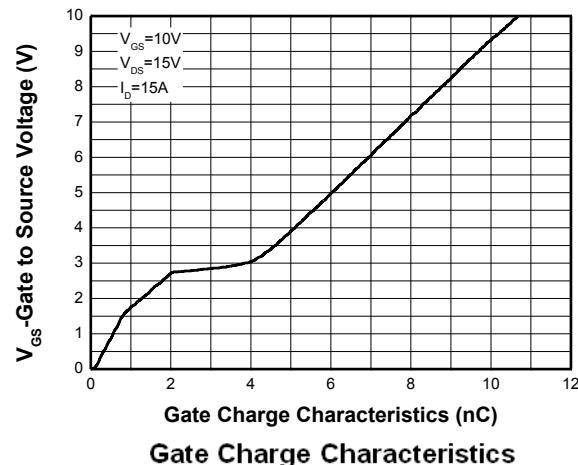
Note:

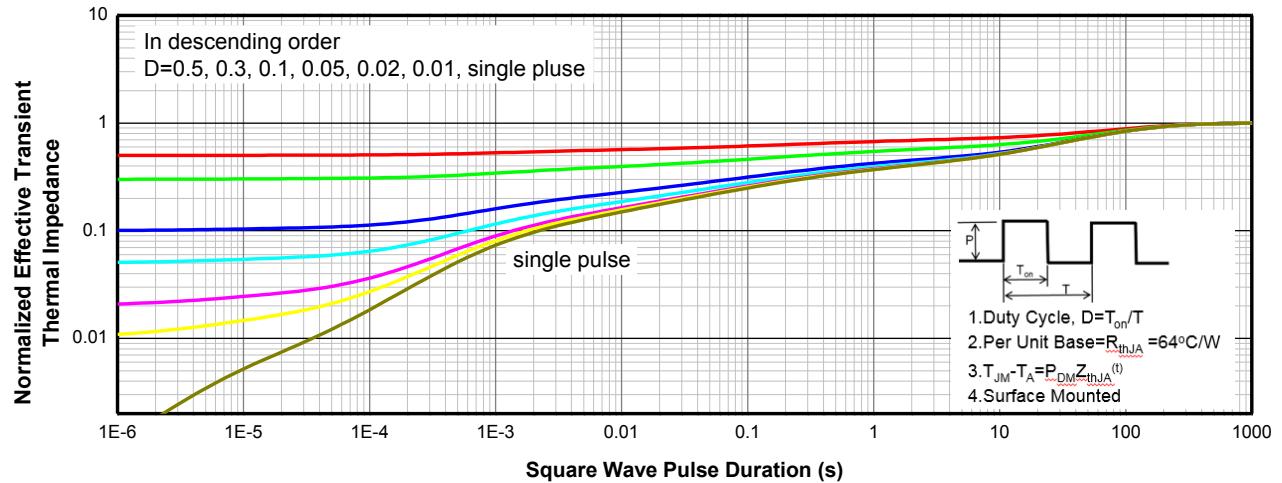
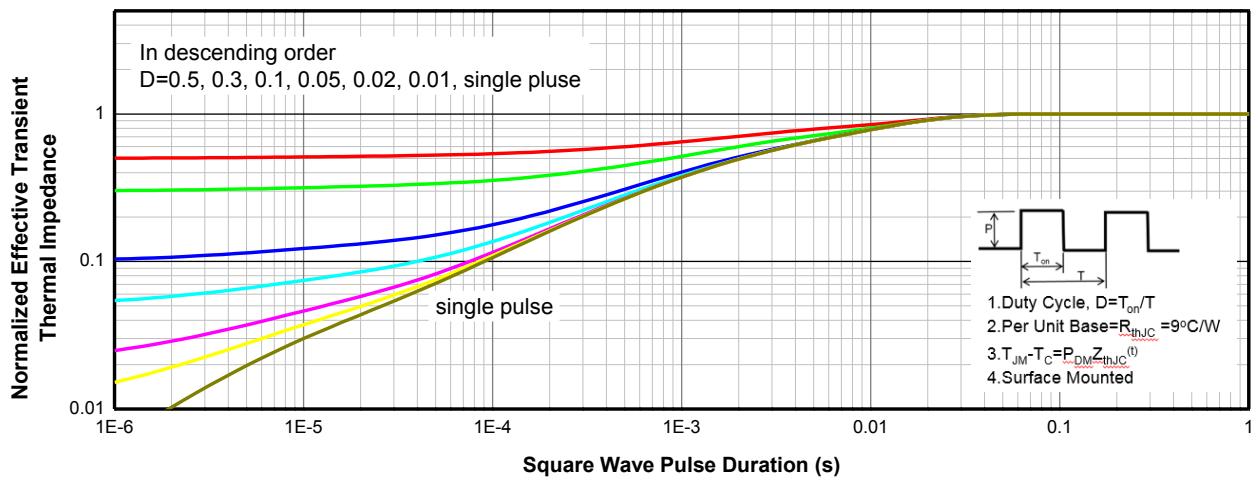
- a The value of R_{θJA} is measured with the device mounted on 1-inch² (6.45cm²) with 2oz.(0.071mm thick) Copper pad on a 1.5*1.5 inch², 0.06-inch thick FR4 PCB, in a still air environment with T_A =25°C. The power dissipation P_{DSM} is based on R_{θJA} t≤10s value and the T_{J(MAX)}=150°C. The value in any given application is determined by the user's specific board design.
- b The power dissipation P_D is based on T_{J(MAX)}=150°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.
- c Repetitive rating, ~10us pulse width, duty cycle ~1%, keep initial T_J =25°C, the maximum allowed junction temperature of 150°C.
- d The maximum current rating by source bonding technology.
- e The static characteristics are obtained using ~380us pulses, duty cycle ~1%.

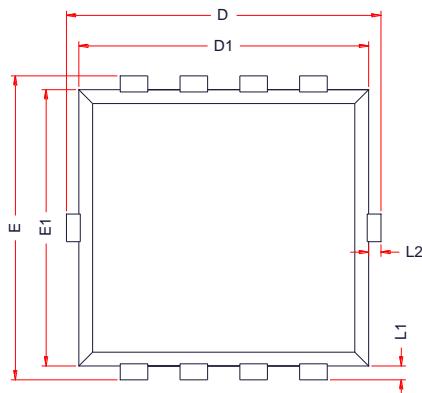
Electronics Characteristics (Ta=25°C, unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
OFF CHARACTERISTICS						
Drain-to-Source Breakdown Voltage	V_{DSS}	$V_{GS} = 0 \text{ V}, I_D = 250\mu\text{A}$	30			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 24\text{V}, V_{GS} = 0\text{V}$			1	μA
Gate-to-source Leakage Current	I_{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20\text{V}$			± 100	nA
ON CHARACTERISTICS						
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_D = 250\mu\text{A}$	1.2	1.7	2.5	V
Drain-to-source On-resistance	$R_{DS(on)}$	$V_{GS} = 10\text{V}, I_D = 10\text{A}$		12.0	15.0	$\text{m}\Omega$
		$V_{GS} = 4.5\text{V}, I_D = 8\text{A}$		17.5	24.5	
Forward Transconductance	g_{FS}	$V_{DS} = 5\text{V}, I_D = 15\text{A}$		9		S
CHARGES, CAPACITANCES AND GATE RESISTANCE						
Input Capacitance	C_{ISS}	$V_{GS} = 0 \text{ V}, f = 1.0\text{MHz}, V_{DS} = 15 \text{ V}$		540		Pf
Output Capacitance	C_{OSS}			95		
Reverse Transfer Capacitance	C_{RSS}			68		
Gate Resistance	R_g	$F=1\text{MHz}$		1.4		Ω
Total Gate Charge	$Q_{G(TOT)}$	$V_{GS} = 10 \text{ V}, V_{DS} = 15 \text{ V}, I_D = 15 \text{ A}$		10.6		nC
Threshold Gate Charge	$Q_{G(TH)}$			1		
Gate-to-Source Charge	Q_{GS}			1.9		
Gate-to-Drain Charge	Q_{GD}			2.1		
SWITCHING CHARACTERISTICS						
Turn-On Delay Time	$t_{d(\text{ON})}$	$V_{GS} = 10 \text{ V}, V_{DS} = 15 \text{ V}, R_L = 1 \Omega, R_G = 3\Omega$		4		ns
Rise Time	t_r			17		
Turn-Off Delay Time	$t_{d(\text{OFF})}$			18		
Fall Time	t_f			9		
BODY DIODE CHARACTERISTICS						
Forward Voltage	V_{SD}	$V_{GS} = 0 \text{ V}, I_S = 1\text{A}$		0.7	1.2	V

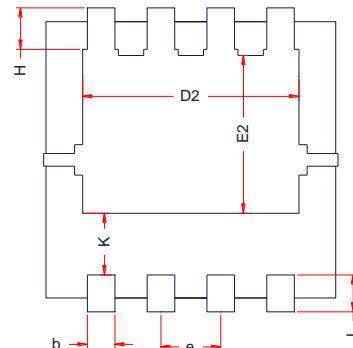
Typical Characteristics (Ta=25°C, unless otherwise noted)

Output Characteristics ^e

Transfer Characteristics ^e

On-Resistance vs. Drain Current ^e

On-Resistance vs. Gate-to-Source Voltage ^e

On-Resistance vs. Junction Temperature ^e

Threshold Voltage vs. Temperature


Capacitance

Body Diode Forward Voltage ^e

Single pulse power

Safe operating power

Gate Charge Characteristics

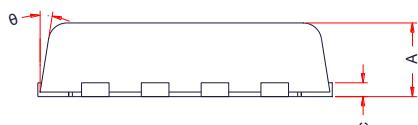
Transient thermal response (Junction-to-Ambient)

Transient thermal response (Junction-to-Case)


PACKAGE OUTLINE DIMENSIONS
PDFN3333-8L


TOP VIEW

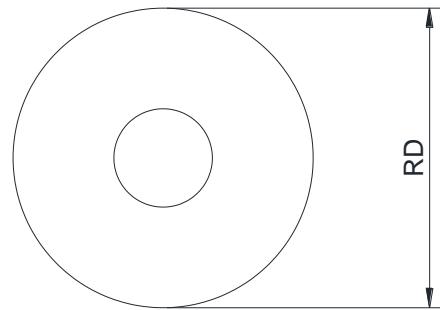
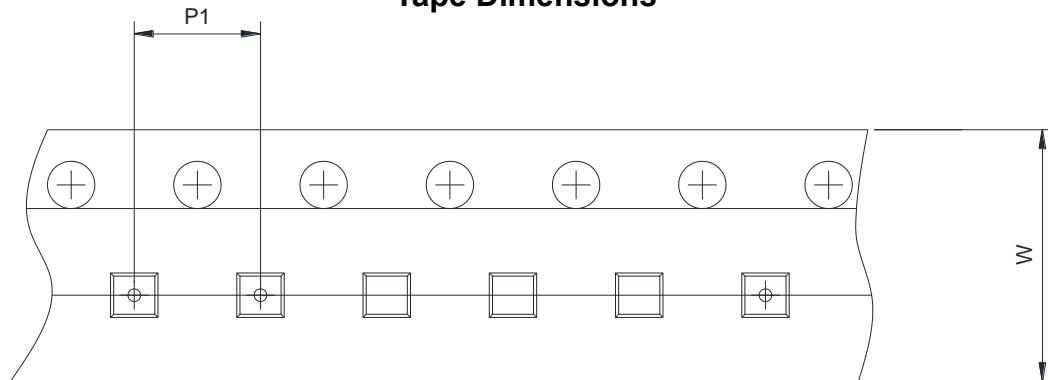
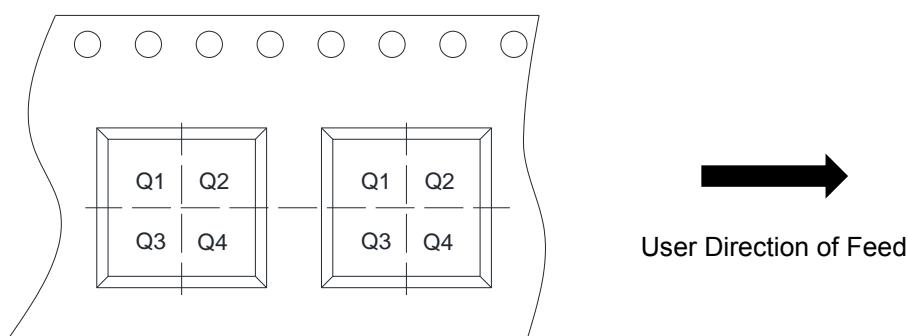


BOTTOM VIEW



SIDE VIEW

Symbol	Dimensions in Millimeters		
	Min.	Typ.	Max.
A	0.70	0.80	0.90
b	0.25	0.30	0.35
c	0.14	0.15	0.20
D	3.10	3.30	3.50
D1	3.05	3.15	3.25
D2	2.35	2.45	2.55
e	0.55	0.65	0.75
E	3.10	3.30	3.50
E1	2.90	3.00	3.10
E2	1.64	1.74	1.84
H	0.32	0.42	0.52
K	0.59	0.69	0.79
L	0.25	0.40	0.55
L1	0.10	0.15	0.20
L2	-	-	0.15
θ	8°	10°	12°

TAPE AND REEL INFORMATION
Reel Dimensions

Tape Dimensions

Quadrant Assignments For PIN1 Orientation In Tape


RD	Reel Dimension	<input type="checkbox"/> 7inch <input checked="" type="checkbox"/> 13inch
W	Overall width of the carrier tape	<input type="checkbox"/> 8mm <input checked="" type="checkbox"/> 12mm <input type="checkbox"/> 16mm
P1	Pitch between successive cavity centers	<input type="checkbox"/> 2mm <input type="checkbox"/> 4mm <input checked="" type="checkbox"/> 8mm
Pin1	Pin1 Quadrant	<input checked="" type="checkbox"/> Q1 <input type="checkbox"/> Q2 <input type="checkbox"/> Q3 <input type="checkbox"/> Q4